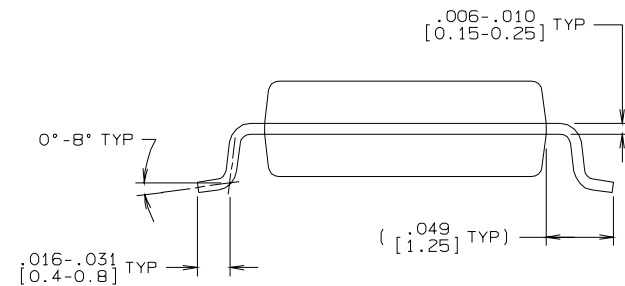
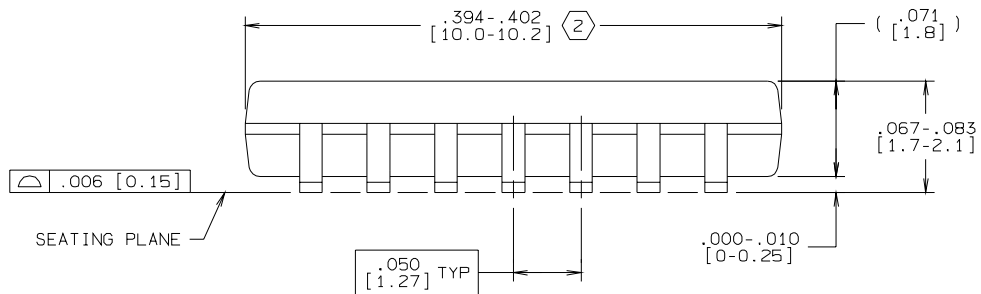
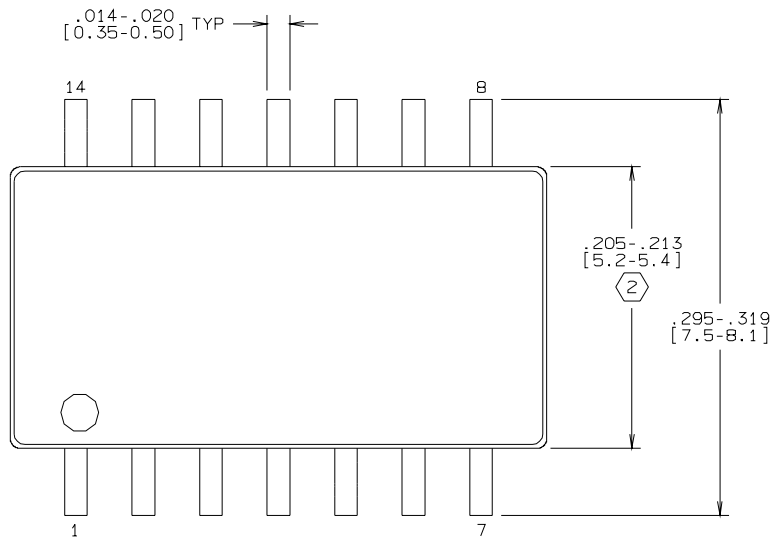


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	0766B	06/28/90	OW/CC
B	TITLE WAS: MOLDED PACKAGE EIAJ, 300 MIL SOP, 14 LEAD; TRANSFER DET F DIM'S TO SIDE VIEW; REMOVE DET F; REDRAW.	10211	01/04/94	MS/



COTROLLING DIMENSION: MILLIMETER

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER PLATED LEAD FINISH.

(2) THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN MARTA SUCHY	01/04/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DF TG. CHK.		MOLDED SOP, EIAJ TYPE II, 14 LEAD		
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-M14D	B
DO NOT SCALE DRAWING		SHEET 1 OF 1		